



PATENT

#10/8  
11/7/02

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: ZHU et al.

Attorney Docket No.: LAM1P147/P0675

Application No.: 09/782,185

Examiner: CHEN, Kin-Chan

Filed: February 12, 2001

Group: 1765

Title: UNIQUE PROCESS CHEMISTRY FOR  
ETCHING ORGANIC LOW-K MATERIALSCERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence and the documents and/or fees referred to as attached therein are being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Box RCE, Commissioner for Patents, Washington, D.C. 20231 on October 31, 2002.

Signed: \_\_\_\_\_

Sue Funchess

**PRELIMINARY AMENDMENT B**

Box RCE  
Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

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In response to the Office Action dated August 5, 2002, please amend the above-identified patent application as follows:

**In the Claims:**

Please cancel claims 1-4, 6, and 8-18, without prejudice, and add claims 19-37 as follows:

19. (New) A method for etching a feature in an integrated circuit wafer, the wafer incorporating at least one low-k dielectric layer partially disposed below a hardmask, the method comprising:

disposing the wafer within a reaction chamber;

introducing a flow of etchant gas comprising a fluorocarbon and an active etchant into the reaction chamber;